

## SN74LVC1G19 1-of-2 Decoder and Demultiplexer

### 1 Features

- Available in the Texas Instruments NanoFree™ Package
- Supports 5-V  $V_{CC}$  Operation
- Inputs Accept Voltages to 5.5 V
- Supports Down Translation to  $V_{CC}$
- Maximum  $t_{pd}$  of 4 ns at 3.3 V
- Low Power Consumption, 10- $\mu$ A Maximum  $I_{CC}$
- $\pm 24$ -mA Output Drive at 3.3 V
- $V_{OLP}$  (Output Ground Bounce) <0.8 V Typical at  $V_{CC} = 3.3$  V,  $T_A = 25^\circ\text{C}$
- $V_{OHV}$  (Output  $V_{OH}$  Undershoot) >2 V Typical at  $V_{CC} = 3.3$  V,  $T_A = 25^\circ\text{C}$
- $I_{off}$  Supports Live Insertion, Partial-Power-Down Mode, and Back-Drive Protection
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
  - 2000-V Human Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)

### 2 Applications

- AV Receivers
- Audio Docks: Portable
- Blu-ray® Players and Home Theater
- MP3 Players/Recorders
- Personal Digital Assistants (PDAs)
- Power: Telecom/Server AC/DC Supply: Single Controller: Analog and Digital
- Solid State Drives (SSDs): Client and Enterprise
- TVs: LCD/Digital and High-Definition (HDTVs)
- Tablets: Enterprise
- Video Analytics: Server
- Wireless Headsets, Keyboards, and Mice

### 3 Description

This decoder/demultiplexer is designed for 1.65-V to 5.5-V  $V_{CC}$  operation.

The SN74LVC1G19 device is a 1-of-2 decoder / demultiplexer. When  $\bar{E}$  input is high, the decoder will be disabled and both outputs will be high. When  $\bar{E}$  input is low, the A input selects which output will be low.

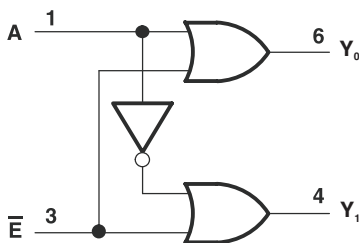
This device is fully specified for partial-power-down applications using  $I_{off}$ .

#### Device Information<sup>(1)</sup>

PART NUMBER	PACKAGE	BODY SIZE (NOM)
SN74LVC1G19DBV	SOT-23 (6)	2.9 mm × 1.6 mm
SN74LVC1G19DCK	SC70 (6)	2.0 mm × 1.25 mm
SN74LVC1G19DRL	SOT (6)	1.6 mm × 1.2 mm
SN74LVC1G19DRY	SON (6)	1.45 mm × 1.0 mm
SN74LVC1G19YZP	DSBGA (6)	1.41 mm × 0.91 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

#### Simplified Schematic



## Table of Contents

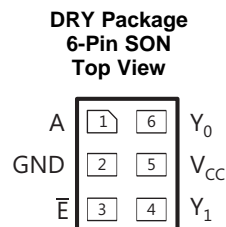
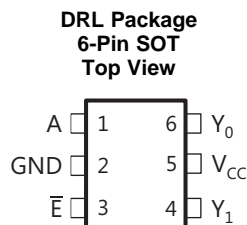
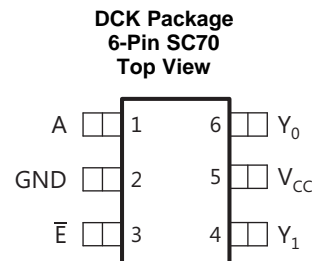
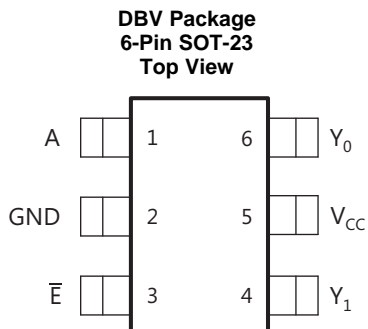
<b>1 Features</b> .....	<b>1</b>	8.1 Overview .....	<b>10</b>
<b>2 Applications</b> .....	<b>1</b>	8.2 Functional Block Diagram .....	<b>10</b>
<b>3 Description</b> .....	<b>1</b>	8.3 Feature Description .....	<b>10</b>
<b>4 Revision History</b> .....	<b>2</b>	8.4 Device Functional Modes .....	<b>10</b>
<b>5 Pin Configuration and Functions</b> .....	<b>3</b>	<b>9 Application and Implementation</b> .....	<b>11</b>
<b>6 Specifications</b> .....	<b>4</b>	9.1 Application Information .....	<b>11</b>
6.1 Absolute Maximum Ratings .....	<b>4</b>	9.2 Typical Application .....	<b>11</b>
6.2 ESD Ratings .....	<b>4</b>	<b>10 Power Supply Recommendations</b> .....	<b>12</b>
6.3 Recommended Operating Conditions .....	<b>5</b>	<b>11 Layout</b> .....	<b>12</b>
6.4 Thermal Information .....	<b>5</b>	11.1 Layout Guidelines .....	<b>12</b>
6.5 Electrical Characteristics .....	<b>6</b>	11.2 Layout Example .....	<b>12</b>
6.6 Switching Characteristics, $C_L = 15$ pF .....	<b>6</b>	<b>12 Device and Documentation Support</b> .....	<b>13</b>
6.7 Switching Characteristics, $C_L = 30$ pF or 50 pF .....	<b>6</b>	12.1 Community Resources .....	<b>13</b>
6.8 Operating Characteristics .....	<b>6</b>	12.2 Trademarks .....	<b>13</b>
6.9 Typical Characteristics .....	<b>7</b>	12.3 Electrostatic Discharge Caution .....	<b>13</b>
<b>7 Parameter Measurement Information</b> .....	<b>8</b>	12.4 Glossary .....	<b>13</b>
<b>8 Detailed Description</b> .....	<b>10</b>	<b>13 Mechanical, Packaging, and Orderable Information</b> .....	<b>13</b>

## 4 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

<b>Changes from Revision F (July 2012) to Revision G</b>	<b>Page</b>
• Added <i>Applications</i> section, <i>Device Information</i> table, <i>Pin Configuration and Functions</i> section, <i>ESD Ratings</i> table, <i>Thermal Information</i> table, <i>Feature Description</i> section, <i>Device Functional Modes</i> , <i>Application and Implementation</i> section, <i>Power Supply Recommendations</i> section, <i>Layout</i> section, <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section .....	<b>1</b>
• Deleted <i>Ordering Information</i> table. ....	<b>1</b>
• Updated $I_{off}$ in <i>Features</i> . ....	<b>1</b>

## 5 Pin Configuration and Functions



**YZP Package  
6-Pin DSBGA  
Bottom View**



### Pin Functions<sup>(1)</sup>

PIN		I/O	DESCRIPTION
NAME	NO.		
A	1	I	Adress input, selects which output goes low.
GND	2	—	Ground
$\bar{E}$	3	I	Enable input, active low
$Y_1$	4	O	Output 1, low when selected by A high and $\bar{E}$ low
$V_{CC}$	5	—	Power pin
$Y_0$	6	O	Output 0, low when selected by A low and $\bar{E}$ low

(1) See mechanical drawings for dimensions

## 6 Specifications

### 6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage	–0.5	6.5	V
V <sub>I</sub>	Input voltage <sup>(2)</sup>	–0.5	6.5	V
V <sub>O</sub>	Voltage applied to any output in the high-impedance or power-off state <sup>(2)</sup>	–0.5	6.5	V
V <sub>O</sub>	Voltage applied to any output in the high or low state <sup>(2)(3)</sup>	–0.5	V <sub>CC</sub> + 0.5	V
I <sub>IK</sub>	Input clamp current	V <sub>I</sub> < 0	–50	mA
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0	–50	mA
I <sub>O</sub>	Continuous output current		±50	mA
	Continuous current through V <sub>CC</sub> or GND		±100	mA
T <sub>stg</sub>	Storage temperature	–65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The value of V<sub>CC</sub> is provided in the *Recommended Operating Conditions* table.

### 6.2 ESD Ratings

		VALUE	UNIT
V <sub>ESD</sub>	Electrostatic discharge	Human Body Model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins <sup>(1)</sup>	±2000
		Charged-Device Model (CDM), per JEDEC specification JESD22-C101, all pins <sup>(2)</sup>	±1000
		Machine model	±200

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 6.3 Recommended Operating Conditions

 over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

			MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage	Operating	1.65	5.5	V
		Data retention only	1.5		
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 1.65 V to 1.95 V	0.65 × V <sub>CC</sub>		V
		V <sub>CC</sub> = 2.3 V to 2.7 V	1.7		
		V <sub>CC</sub> = 3 V to 3.6 V	2		
		V <sub>CC</sub> = 4.5 V to 5.5 V	0.7 × V <sub>CC</sub>		
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 1.65 V to 1.95 V		0.35 × V <sub>CC</sub>	V
		V <sub>CC</sub> = 2.3 V to 2.7 V		0.7	
		V <sub>CC</sub> = 3 V to 3.6 V		0.8	
		V <sub>CC</sub> = 4.5 V to 5.5 V		0.3 × V <sub>CC</sub>	
V <sub>I</sub>	Input voltage		0	5.5	V
V <sub>O</sub>	Output voltage		0	V <sub>CC</sub>	V
I <sub>OH</sub>	High-level output current	V <sub>CC</sub> = 1.65 V		–4	mA
		V <sub>CC</sub> = 2.3 V		–8	
		V <sub>CC</sub> = 3 V		–16	
		V <sub>CC</sub> = 4.5 V		–24	
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 1.65 V		4	mA
		V <sub>CC</sub> = 2.3 V		8	
		V <sub>CC</sub> = 3 V		16	
		V <sub>CC</sub> = 4.5 V		24	
Δt/Δv	Input transition rise or fall rate	V <sub>CC</sub> = 1.8 V ± 0.15 V, 2.5 V ± 0.2 V		20	ns/V
		V <sub>CC</sub> = 3.3 V ± 0.3 V		10	
		V <sub>CC</sub> = 5 V ± 0.5 V		5	
T <sub>A</sub>	Operating free-air temperature		–40	85	°C

(1) All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, [SCBA004](#).

### 6.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>	SN74LVC1G19					UNIT	
	DBV (SOT-23)	DCK (SC70)	DRL (SOT)	DRY (SON)	YZP (DSBGA)		
	6 PINS	6 PINS	6 PINS	6 PINS	6 PINS		
R <sub>θJA</sub>	Junction-to-ambient thermal resistance	165	259	142	234	123	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, [SPRA953](#).

## 6.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	MIN	TYP <sup>(1)</sup>	MAX	UNIT
V <sub>OH</sub>	I <sub>OH</sub> = -100 μA	1.65 V to 5.5 V	V <sub>CC</sub> - 0.1			V
	I <sub>OH</sub> = -4 mA	1.65 V	1.2			
	I <sub>OH</sub> = -8 mA	2.3 V	1.9			
	I <sub>OH</sub> = -16 mA	3 V	2.4			
	I <sub>OH</sub> = -24 mA		2.3			
	I <sub>OH</sub> = -32 mA	4.5 V	3.8			
V <sub>OL</sub>	I <sub>OL</sub> = 100 μA	1.65 V to 5.5 V			0.1	V
	I <sub>OL</sub> = 4 mA	1.65 V			0.45	
	I <sub>OL</sub> = 8 mA	2.3 V			0.3	
	I <sub>OL</sub> = 16 mA	3 V			0.4	
	I <sub>OL</sub> = 24 mA				0.55	
	I <sub>OL</sub> = 32 mA	4.5 V			0.55	
I <sub>I</sub>	V <sub>I</sub> = 5.5 V or GND	0 to 5.5 V			±1	μA
I <sub>off</sub>	V <sub>I</sub> or V <sub>O</sub> = 5.5 V	0			±10	μA
I <sub>CC</sub>	V <sub>I</sub> = 5.5 V or GND, I <sub>O</sub> = 0	1.65 V to 5.5 V			10	μA
ΔI <sub>CC</sub>	One input at V <sub>CC</sub> - 0.6 V, Other inputs at V <sub>CC</sub> or GND	3 V to 5.5 V			500	μA
C <sub>I</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND	3.3 V		3.5		pF

 (1) All typical values are at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C.

## 6.6 Switching Characteristics, C<sub>L</sub> = 15 pF

 over recommended operating free-air temperature range, C<sub>L</sub> = 15 pF (unless otherwise noted) (see [Figure 3](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 1.8 V ± 0.15 V		V <sub>CC</sub> = 2.5 V ± 0.2 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		V <sub>CC</sub> = 5 V ± 0.5 V		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t <sub>pd</sub>	A or $\bar{E}$	Y	2.5	16.1	1.5	5.9	1	4	0.5	2.8	ns

## 6.7 Switching Characteristics, C<sub>L</sub> = 30 pF or 50 pF

 over recommended operating free-air temperature range, C<sub>L</sub> = 30 pF or 50 pF (unless otherwise noted) (see [Figure 4](#))

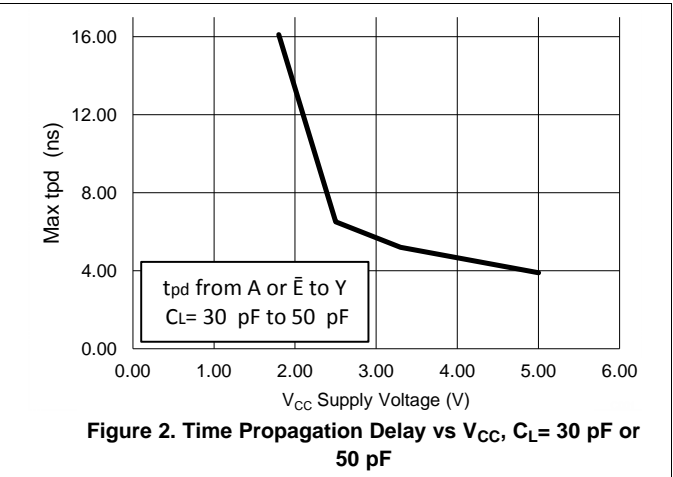
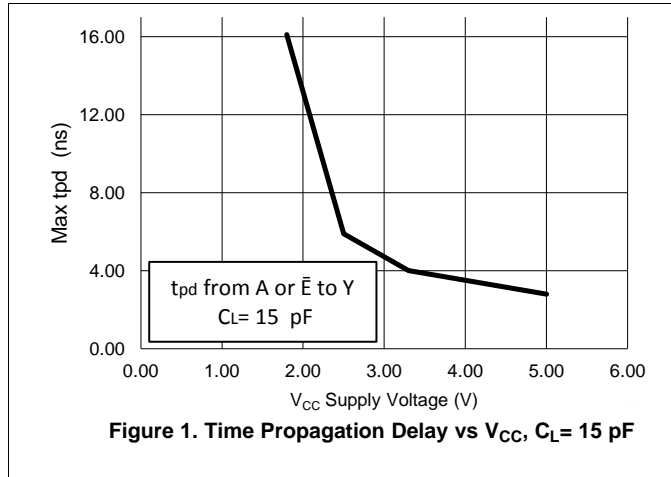
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 1.8 V ± 0.15 V		V <sub>CC</sub> = 2.5 V ± 0.2 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		V <sub>CC</sub> = 5 V ± 0.5 V		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t <sub>pd</sub>	A or $\bar{E}$	Y	3.2	16.1	1.5	6.5	1.1	5.2	0.5	3.9	ns

## 6.8 Operating Characteristics

 T<sub>A</sub> = 25°C

PARAMETER	TEST CONDITIONS	V <sub>CC</sub> = 1.8 V	V <sub>CC</sub> = 2.5 V	V <sub>CC</sub> = 3.3 V	V <sub>CC</sub> = 5 V	UNIT
		TYP	TYP	TYP	TYP	
C <sub>pd</sub>	Power dissipation capacitance f = 10 MHz	15.5	16	16	18	pF

## 6.9 Typical Characteristics



## 7 Parameter Measurement Information



TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	$V_{LOAD}$
$t_{PHZ}/t_{PZH}$	GND

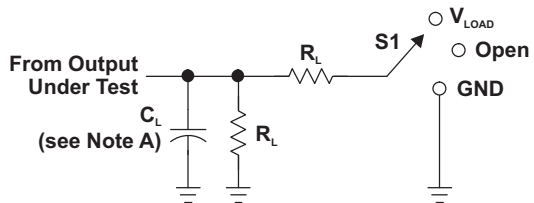
$V_{CC}$	INPUTS		$V_M$	$V_{LOAD}$	$C_L$	$R_L$	$V_{\Delta}$
	$V_i$	$t_i/t_r$					
$1.8\text{ V} \pm 0.15\text{ V}$	$V_{CC}$	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	15 pF	1 M $\Omega$	0.15 V
$2.5\text{ V} \pm 0.2\text{ V}$	$V_{CC}$	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	15 pF	1 M $\Omega$	0.15 V
$3.3\text{ V} \pm 0.3\text{ V}$	3 V	$\leq 2.5\text{ ns}$	1.5 V	6 V	15 pF	1 M $\Omega$	0.3 V
$5\text{ V} \pm 0.5\text{ V}$	$V_{CC}$	$\leq 2.5\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	15 pF	1 M $\Omega$	0.3 V



- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.  
 C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_o = 50\ \Omega$ .  
 D. The outputs are measured one at a time, with one transition per measurement.  
 E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .  
 F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .  
 G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .  
 H. All parameters and waveforms are not applicable to all devices.

**Figure 3. Load Circuit and Voltage Waveforms**

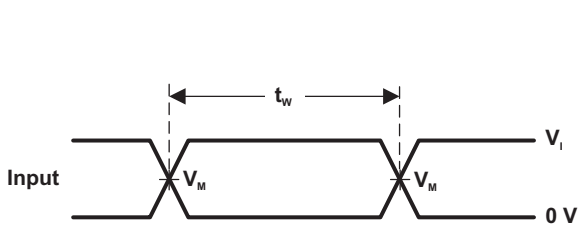
Parameter Measurement Information (continued)



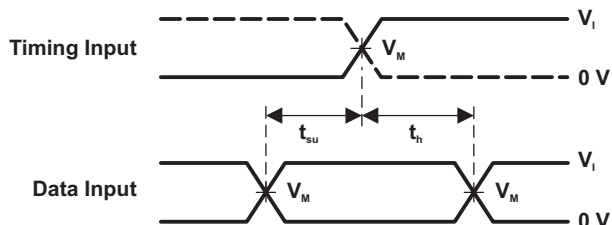
LOAD CIRCUIT

TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	$V_{LOAD}$
$t_{PHZ}/t_{PZH}$	GND

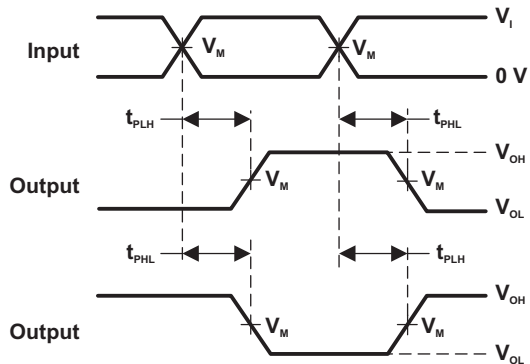
$V_{CC}$	INPUTS		$V_M$	$V_{LOAD}$	$C_L$	$R_L$	$V_{\Delta}$
	$V_I$	$t_r/t_f$					
$1.8\text{ V} \pm 0.15\text{ V}$	$V_{CC}$	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	1 k $\Omega$	0.15 V
$2.5\text{ V} \pm 0.2\text{ V}$	$V_{CC}$	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	500 $\Omega$	0.15 V
$3.3\text{ V} \pm 0.3\text{ V}$	3 V	$\leq 2.5\text{ ns}$	1.5 V	6 V	50 pF	500 $\Omega$	0.3 V
$5\text{ V} \pm 0.5\text{ V}$	$V_{CC}$	$\leq 2.5\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	50 pF	500 $\Omega$	0.3 V



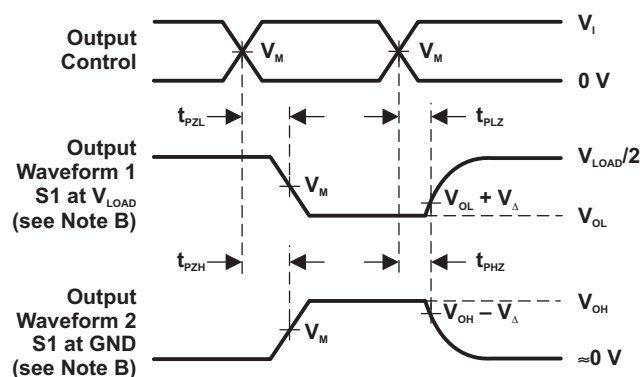
VOLTAGE WAVEFORMS PULSE DURATION



VOLTAGE WAVEFORMS SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS PROPAGATION DELAY TIMES INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS ENABLE AND DISABLE TIMES LOW- AND HIGH-LEVEL ENABLING

- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.  
 C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_o = 50\ \Omega$ .  
 D. The outputs are measured one at a time, with one transition per measurement.  
 E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .  
 F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{on}$ .  
 G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .  
 H. All parameters and waveforms are not applicable to all devices.

Figure 4. Load Circuit and Voltage Waveforms

## 8 Detailed Description

### 8.1 Overview

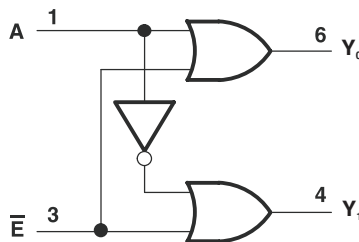
This decoder/demultiplexer is designed for 1.65-V to 5.5-V  $V_{CC}$  operation.

The SN74LVC1G19 device is a 1-of-2 decoder/demultiplexer. This device decodes the 1-bit address on input A and places a logic low on the matching address output,  $Y_0$  or  $Y_1$ , when the enable ( $\bar{E}$ ) input signal is low.

This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

NanoFree package technology is a major breakthrough in IC packaging concepts, using the die as the package.

### 8.2 Functional Block Diagram



### 8.3 Feature Description

SN74LVC1G19 is available in NanoFree package. NanoFree is a major breakthrough in IC packaging concepts, it is a bare die package developed for applications that require the smallest possible package. The device supports 5-V  $V_{CC}$  Operation. All Inputs accept voltages up to 5.5 V.  $\pm 24$ -mA output drive at 3.3 V. The maximum time propagation delay ( $t_{pd}$ ) is 5.4 ns at 3.3 V. Low Power Consumption, 10- $\mu$ A Max  $I_{CC}$ . Typical output ground bounce ( $V_{OLP}$ ) and Output  $V_{OH}$  Undershoot ( $V_{OHV}$ ). This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  feature ensures that damaging current will not backflow through the device when it is powered down. The SN74LVC1G19 device has isolation during power off.  $I_{off}$  supports live insertion, partial-power-down mode and back drive protection.

### 8.4 Device Functional Modes

Table 1 lists the functional modes of the SN74LVC1G19.

**Table 1. Function Table**

INPUTS		OUTPUTS	
$\bar{E}$	A	$Y_0$	$Y_1$
L	L	L	H
L	H	H	L
H	X	H	H

## 9 Application and Implementation

### NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

### 9.1 Application Information

The SN74LVC1G19 device is a 1-of-2 decoder/demultiplexer. This device decodes the 1 bit address on input A and places a logic low on the matching address output,  $Y_0$  or  $Y_1$ , when the enable ( $\bar{E}$ ) input signal is low. It can produce 24 mA of drive current at 3.3 V making it ideal for driving multiple outputs.

### 9.2 Typical Application

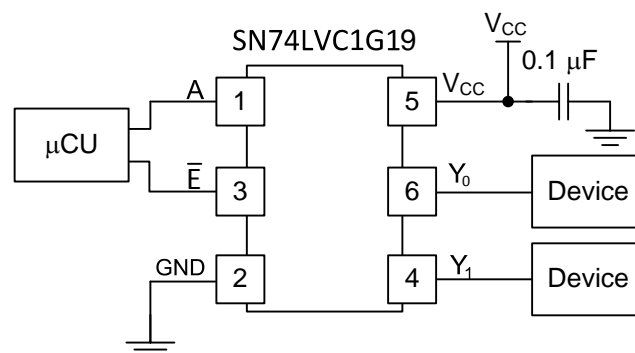


Figure 5. Typical Application Diagram

#### 9.2.1 Design Requirements

This device uses CMOS technology and has balanced output drive. Take care to avoid bus contention because it can drive currents that would exceed maximum limits. Outputs can be combined to produce higher drive but the high drive will also create faster edges into light loads so routing and load conditions should be considered to prevent ringing.

#### 9.2.2 Detailed Design Procedure

##### 1. Recommended Input Conditions:

- For rise time and fall time specifications, see  $(\Delta t/\Delta V)$  in [Recommended Operating Conditions](#) table.
- For specified high and low levels, see  $(V_{IH}$  and  $V_{IL})$  in [Recommended Operating Conditions](#) table.
- Inputs are overvoltage tolerant allowing them to go as high as 5.5 V at any valid  $V_{CC}$ .

##### 2. Recommend Output Conditions:

- Load currents must not exceed 50 mA per output and 100 mA total for the part.
- Series resistors on the output may be used if the user desires to slow the output edge signal or limit the output current.

## Typical Application (continued)

### 9.2.3 Application Curve

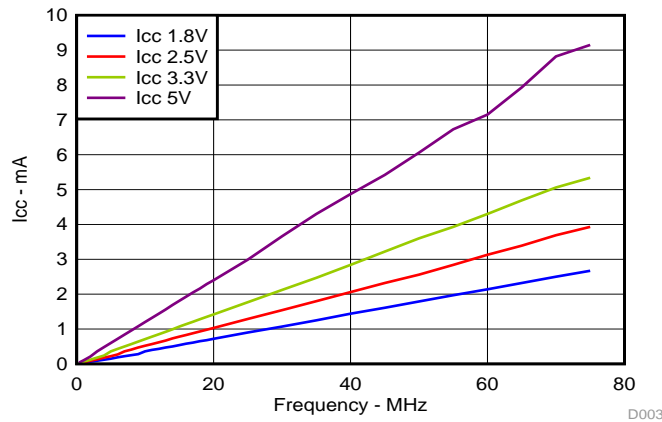


Figure 6. I<sub>CC</sub> vs Frequency

## 10 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in [Absolute Maximum Ratings](#) table.

Each V<sub>CC</sub> terminal must have a good bypass capacitor to prevent power disturbance. For devices with a single supply, a 0.1-μF capacitor is recommended. If there are multiple V<sub>CC</sub> terminals then 0.01-μF or 0.022-μF capacitors are recommended for each power terminal. It is ok to parallel multiple bypass capacitors to reject different frequencies of noise. Multiple bypass capacitors may be paralleled to reject different frequencies of noise. The bypass capacitor must be installed as close to the power terminal as possible for the best results.

## 11 Layout

### 11.1 Layout Guidelines

When using multiple bit logic devices, inputs must not float. In many cases, functions or parts of functions of digital logic devices are unused. Some examples are when only two inputs of a triple-input AND gate are used, or when only 3 of the 4-buffer gates are used. Such input pins must not be left unconnected because the undefined voltages at the outside connections result in undefined operational states.

Specified in [Figure 7](#) are rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that must be applied to any particular unused input depends on the function of the device. Generally they will be tied to GND or V<sub>CC</sub>, whichever makes more sense or is more convenient.

### 11.2 Layout Example

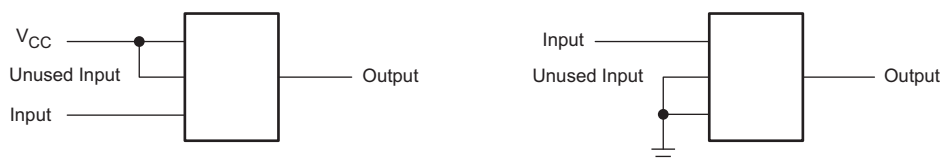


Figure 7. Layout Diagram

## 12 Device and Documentation Support

### 12.1 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

**TI E2E™ Online Community** *TI's Engineer-to-Engineer (E2E) Community*. Created to foster collaboration among engineers. At [e2e.ti.com](http://e2e.ti.com), you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

**Design Support** *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

### 12.2 Trademarks

NanoFree, E2E are trademarks of Texas Instruments.  
Blu-ray is a registered trademark of Blu-ray Disc Association.  
All other trademarks are the property of their respective owners.

### 12.3 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

### 12.4 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

## 13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical packaging and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser based versions of this data sheet, refer to the left hand navigation.

**PACKAGING INFORMATION**

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">SN74LVC1G19DBVR</a>	Active	Production	SOT-23 (DBV)   6	3000   LARGE T&R	Yes	NIPDAU   SN	Level-1-260C-UNLIM	-40 to 85	(C195, C19R)
SN74LVC1G19DBVR.B	Active	Production	SOT-23 (DBV)   6	3000   LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	(C195, C19R)
SN74LVC1G19DBVRE4	Active	Production	SOT-23 (DBV)   6	3000   LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	(C195, C19R)
<a href="#">SN74LVC1G19DBVT</a>	Active	Production	SOT-23 (DBV)   6	250   SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	(C195, C19R)
SN74LVC1G19DBVT.B	Active	Production	SOT-23 (DBV)   6	250   SMALL T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	(C195, C19R)
<a href="#">SN74LVC1G19DCKR</a>	Active	Production	SC70 (DCK)   6	3000   LARGE T&R	Yes	NIPDAU   SN	Level-1-260C-UNLIM	-40 to 85	(CY5, CYF, CYK, CYR)
SN74LVC1G19DCKR.B	Active	Production	SC70 (DCK)   6	3000   LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	(CY5, CYF, CYK, CYR)
SN74LVC1G19DCKRE4	Active	Production	SC70 (DCK)   6	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CY5
<a href="#">SN74LVC1G19DCKRG4</a>	Active	Production	SC70 (DCK)   6	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CY5
SN74LVC1G19DCKRG4.B	Active	Production	SC70 (DCK)   6	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CY5
<a href="#">SN74LVC1G19DRLR</a>	Active	Production	SOT-5X3 (DRL)   6	4000   LARGE T&R	Yes	NIPDAU   NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	(1JZ, CY7, CYR)
SN74LVC1G19DRLR.B	Active	Production	SOT-5X3 (DRL)   6	4000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	(1JZ, CY7, CYR)
SN74LVC1G19DRLRG4	Active	Production	SOT-5X3 (DRL)   6	4000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	(1JZ, CY7, CYR)
<a href="#">SN74LVC1G19DRYR</a>	Active	Production	SON (DRY)   6	5000   LARGE T&R	Yes	Call TI   Nipdau	Level-1-260C-UNLIM	-40 to 85	CY
SN74LVC1G19DRYR.B	Active	Production	SON (DRY)   6	5000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CY
SN74LVC1G19DRYRG4	Active	Production	SON (DRY)   6	5000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CY
SN74LVC1G19DRYRG4.B	Active	Production	SON (DRY)   6	5000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CY
<a href="#">SN74LVC1G19YZPR</a>	Active	Production	DSBGA (YZP)   6	3000   LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 85	(CY7, CYN)
SN74LVC1G19YZPR.B	Active	Production	DSBGA (YZP)   6	3000   LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 85	(CY7, CYN)

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

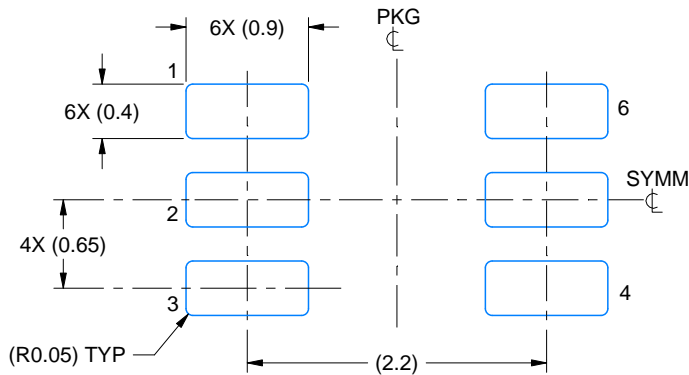
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVC1G19DBVR	SOT-23	DBV	6	3000	180.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
SN74LVC1G19DBVT	SOT-23	DBV	6	250	180.0	8.4	3.23	3.17	1.37	4.0	8.0	Q3
SN74LVC1G19DBVT	SOT-23	DBV	6	250	178.0	9.2	3.3	3.23	1.55	4.0	8.0	Q3
SN74LVC1G19DCKR	SC70	DCK	6	3000	178.0	8.4	2.25	2.45	1.2	4.0	8.0	Q3
SN74LVC1G19DCKRG4	SC70	DCK	6	3000	178.0	9.2	2.4	2.4	1.22	4.0	8.0	Q3
SN74LVC1G19DRLR	SOT-5X3	DRL	6	4000	180.0	8.4	2.0	1.8	0.75	4.0	8.0	Q3
SN74LVC1G19DRYR	SON	DRY	6	5000	180.0	9.5	1.15	1.6	0.75	4.0	8.0	Q1
SN74LVC1G19DRYRG4	SON	DRY	6	5000	180.0	9.5	1.15	1.6	0.75	4.0	8.0	Q1
SN74LVC1G19YZPR	DSBGA	YZP	6	3000	178.0	9.2	1.02	1.52	0.63	4.0	8.0	Q1

**TAPE AND REEL BOX DIMENSIONS**

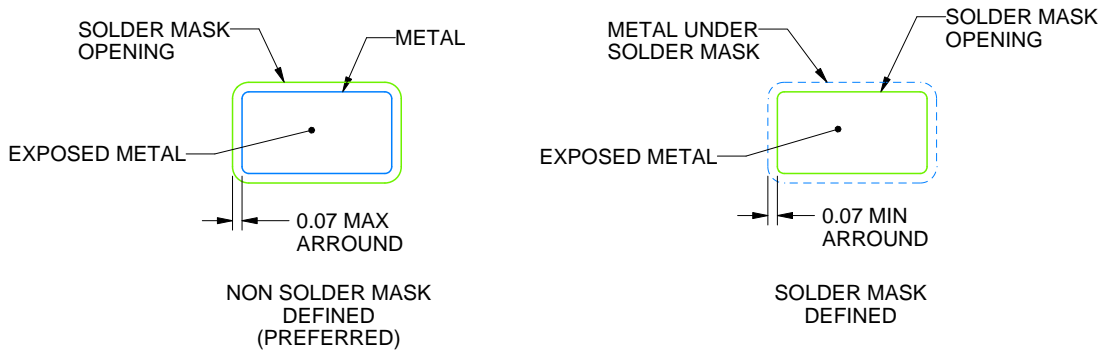

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVC1G19DBVR	SOT-23	DBV	6	3000	210.0	185.0	35.0
SN74LVC1G19DBVT	SOT-23	DBV	6	250	202.0	201.0	28.0
SN74LVC1G19DBVT	SOT-23	DBV	6	250	180.0	180.0	18.0
SN74LVC1G19DCKR	SC70	DCK	6	3000	208.0	191.0	35.0
SN74LVC1G19DCKRG4	SC70	DCK	6	3000	180.0	180.0	18.0
SN74LVC1G19DRLR	SOT-5X3	DRL	6	4000	210.0	185.0	35.0
SN74LVC1G19DRYR	SON	DRY	6	5000	184.0	184.0	19.0
SN74LVC1G19DRYRG4	SON	DRY	6	5000	184.0	184.0	19.0
SN74LVC1G19YZPR	DSBGA	YZP	6	3000	220.0	220.0	35.0





LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:18X

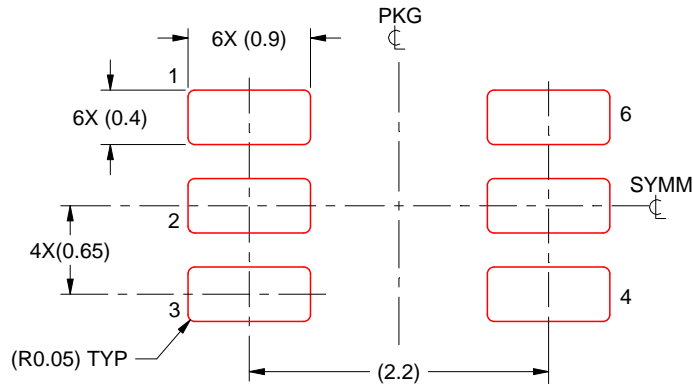


SOLDER MASK DETAILS

4214835/D 11/2024

NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE  
BASED ON 0.125 THICK STENCIL  
SCALE:18X

4214835/D 11/2024

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

## GENERIC PACKAGE VIEW

**DRY 6**

**USON - 0.6 mm max height**

PLASTIC SMALL OUTLINE - NO LEAD



Images above are just a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.

4207181/G

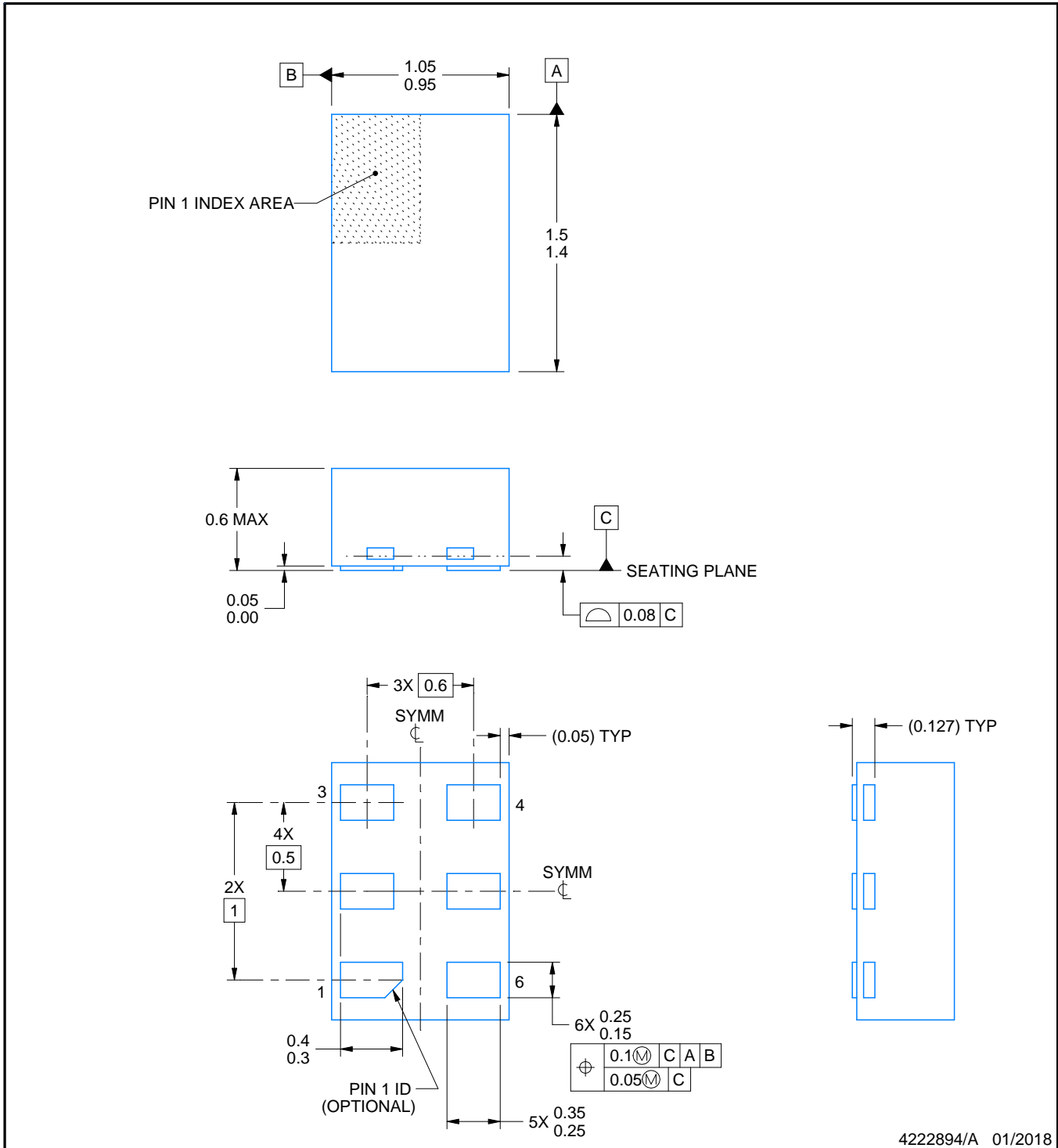
DRY0006A



# PACKAGE OUTLINE

USON - 0.6 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

# EXAMPLE BOARD LAYOUT

DRY0006A

USON - 0.6 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



LAND PATTERN EXAMPLE  
1:1 RATIO WITH PKG SOLDER PADS  
EXPOSED METAL SHOWN  
SCALE:40X



SOLDER MASK DETAILS

4222894/A 01/2018

NOTES: (continued)

3. For more information, see QFN/SON PCB application report in literature No. SLUA271 ([www.ti.com/lit/sluea271](http://www.ti.com/lit/sluea271)).

# EXAMPLE STENCIL DESIGN

DRY0006A

USON - 0.6 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



SOLDER PASTE EXAMPLE  
BASED ON 0.075 - 0.1 mm THICK STENCIL  
SCALE:40X

4222894/A 01/2018

NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

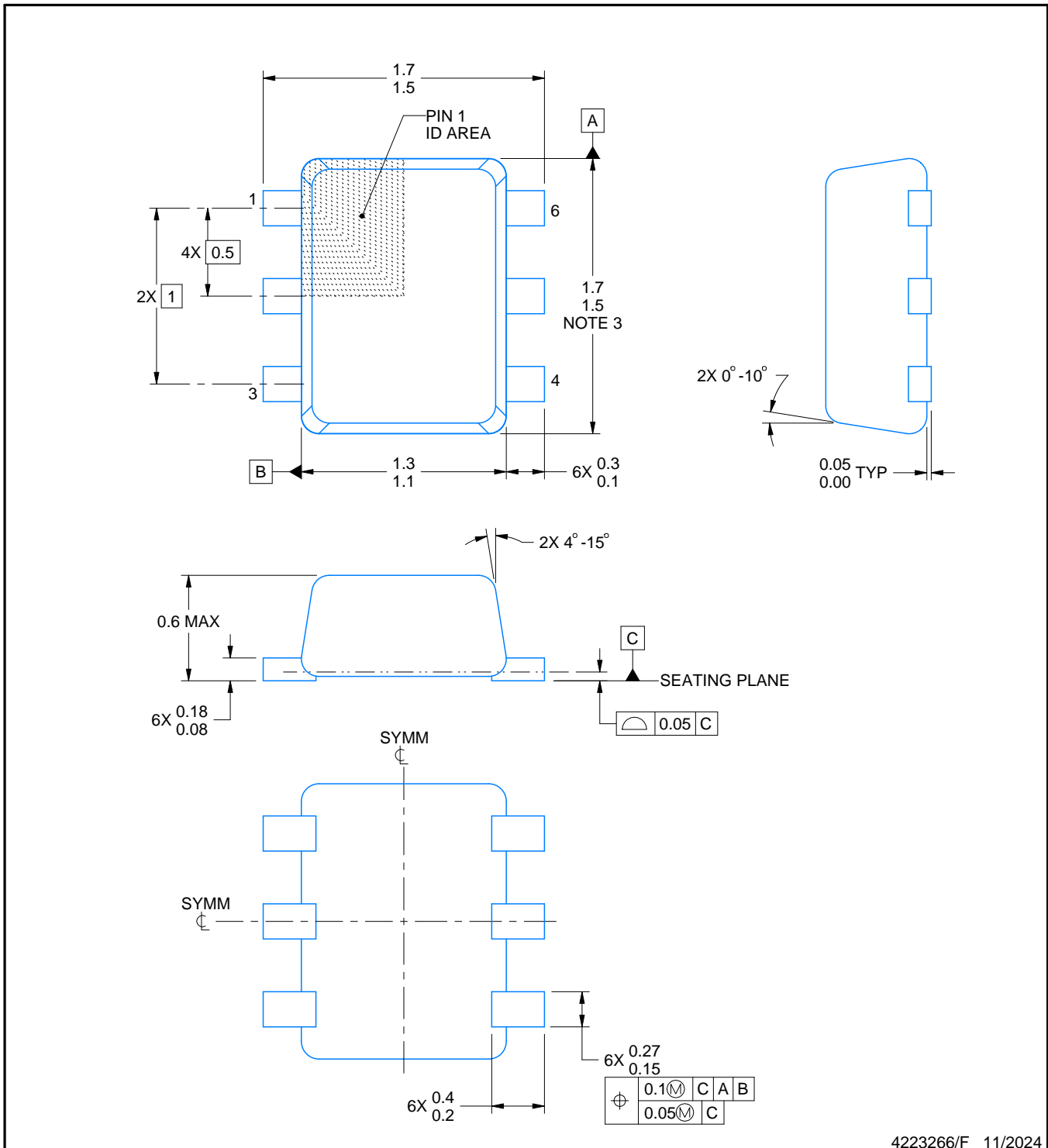
# DRL0006A



# PACKAGE OUTLINE

## SOT - 0.6 mm max height

PLASTIC SMALL OUTLINE



4223266/F 11/2024

### NOTES:

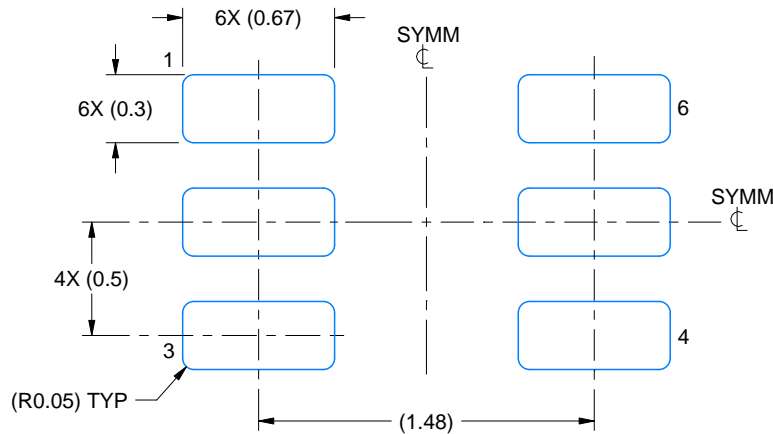
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-293 Variation UAAD

# EXAMPLE BOARD LAYOUT

DRL0006A

SOT - 0.6 mm max height

PLASTIC SMALL OUTLINE



LAND PATTERN EXAMPLE  
SCALE:30X



SOLDERMASK DETAILS

4223266/F 11/2024

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
7. Land pattern design aligns to IPC-610, Bottom Termination Component (BTC) solder joint inspection criteria.

# EXAMPLE STENCIL DESIGN

DRL0006A

SOT - 0.6 mm max height

PLASTIC SMALL OUTLINE



SOLDER PASTE EXAMPLE  
BASED ON 0.1 mm THICK STENCIL  
SCALE:30X

4223266/F 11/2024

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.



# EXAMPLE BOARD LAYOUT

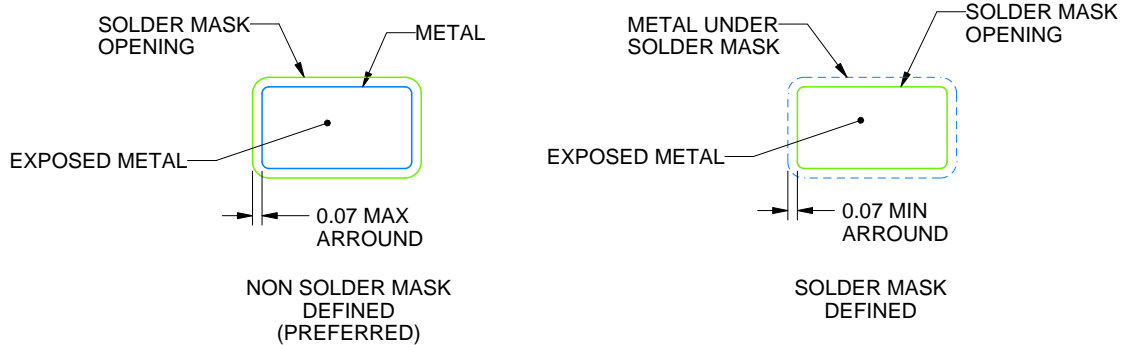
DBV0006A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE:15X



SOLDER MASK DETAILS

4214840/G 08/2024

NOTES: (continued)

- 6. Publication IPC-7351 may have alternate designs.
- 7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

DBV0006A

SOT-23 - 1.45 mm max height

SMALL OUTLINE TRANSISTOR



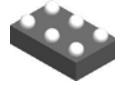
SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:15X

4214840/G 08/2024

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

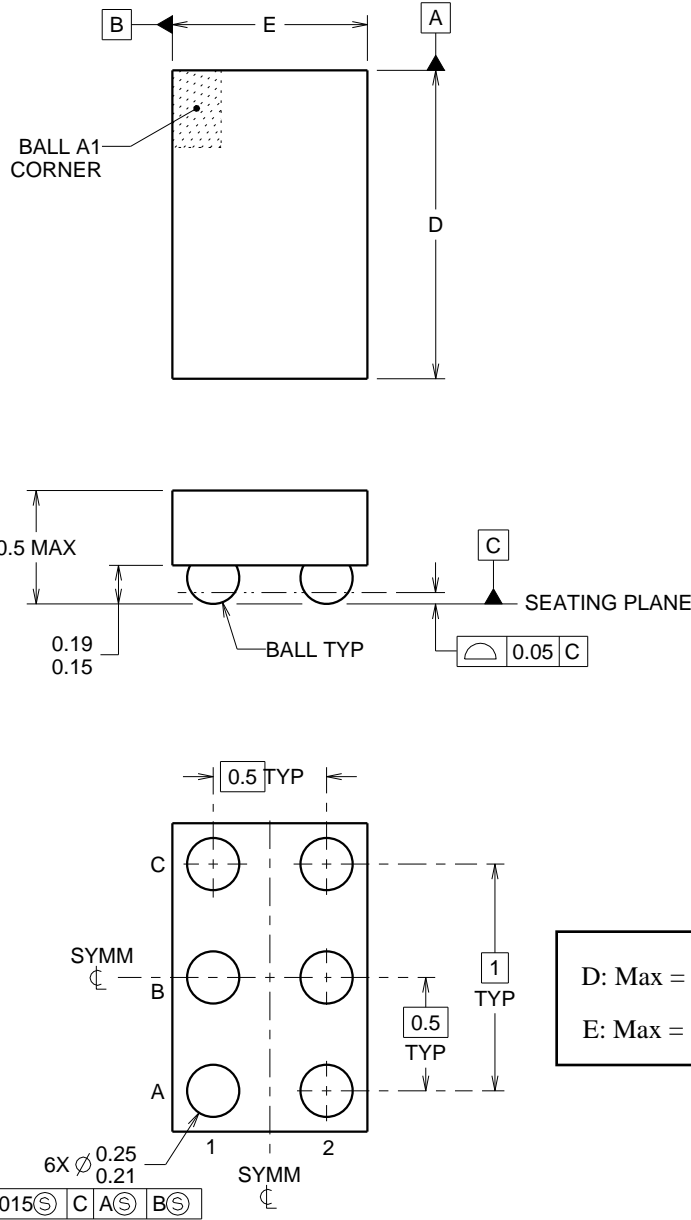
YZP0006



PACKAGE OUTLINE

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



D: Max = 1.418 mm, Min = 1.357 mm  
E: Max = 0.918 mm, Min = 0.857 mm

4219524/A 06/2014

NOTES:

NanoFree Is a trademark of Texas Instruments.

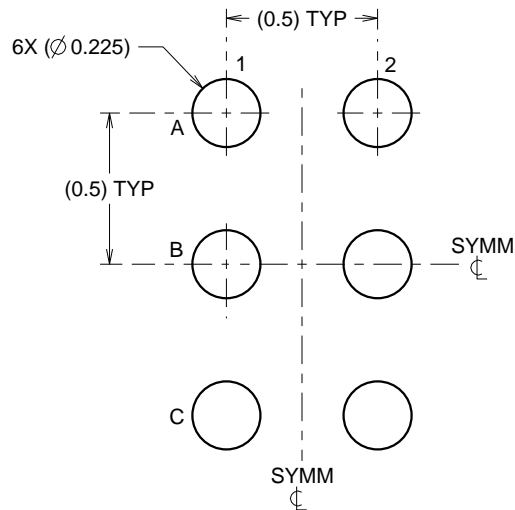
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. NanoFree™ package configuration.

# EXAMPLE BOARD LAYOUT

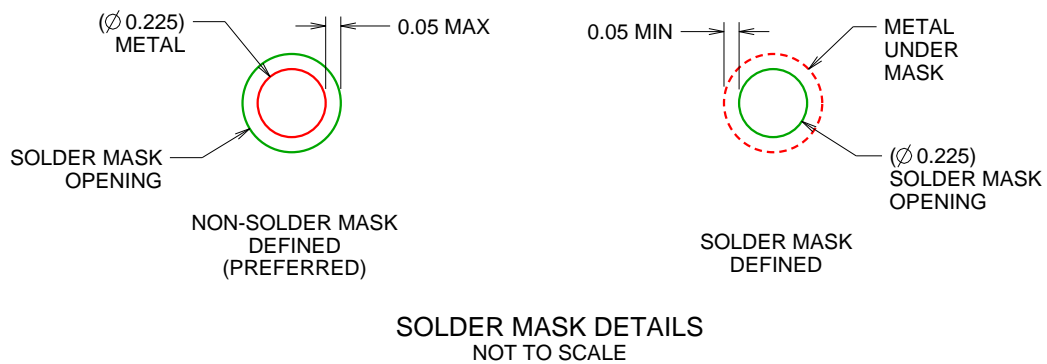
YZP0006

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



LAND PATTERN EXAMPLE  
SCALE:40X



4219524/A 06/2014

NOTES: (continued)

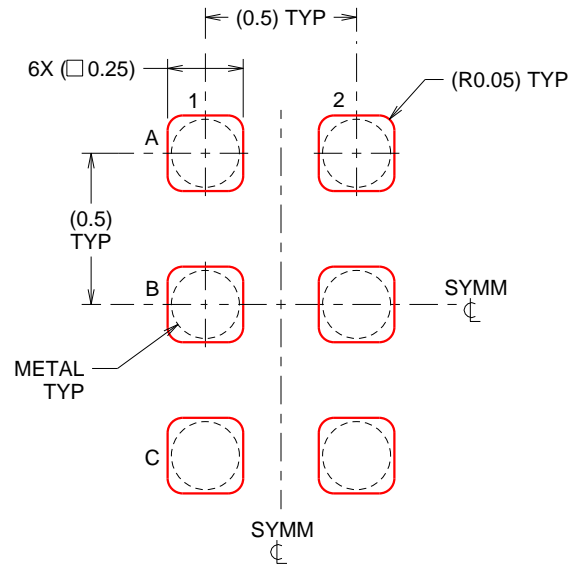
- Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For more information, see Texas Instruments literature number SBVA017 ([www.ti.com/lit/sbva017](http://www.ti.com/lit/sbva017)).

# EXAMPLE STENCIL DESIGN

YZP0006

DSBGA - 0.5 mm max height

DIE SIZE BALL GRID ARRAY



SOLDER PASTE EXAMPLE  
BASED ON 0.1 mm THICK STENCIL  
SCALE:40X

4219524/A 06/2014

NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

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Last updated 10/2025